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SmartPlate System

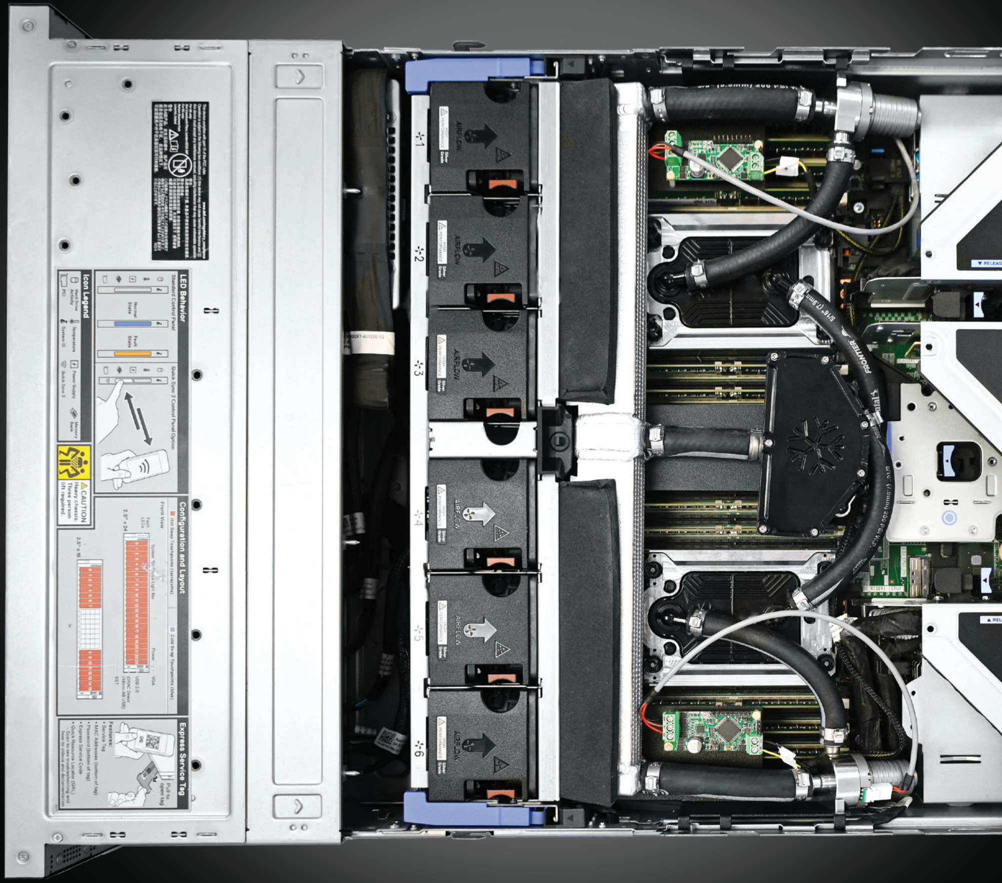
Self-Contained Liquid Cooling for Data Centers

Drive Efficiency and Performance with Self-Contained Liquid Cooling

JetCool's SmartPlate System for Dell PowerEdge servers is a UL-certified, best-in-class self-contained liquid cooling solution that enables immediate time-to-value for customers with an **average of 15% power savings with no piping or plumbing needed**. Popular with compute-intensive verticals ranging from federal and energy to finance, customers deploy the latest CPUs and GPUs without the need for complex infrastructure upgrades, ensuring peak performance and efficiency in demanding environments.

How does it work?

Our patented microconvective cooling® uses arrays of fluid jets to target the hotspots on the industry's most powerful processors. Unlike typical heat sinks or traditional microchannel cold plates that pass fluid over the surface, our cooling jets route fluid directly at the surface, creating an order of magnitude improvement in heat transfer.



— POWERED BY —
DELL Technologies

For more Information and Pricing, Contact Us
hello@jetcool.com | (978) 449-4600 | jetcool.com

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SmartPlate System Datasheet

Unleash Ultimate Computing

Unlock unmatched server performance with SmartPlate System:

- **High-Capacity Cooling:** Efficiently manage extreme workloads, cooling up to 850W in a 1U and 1,200W in a 2U.
- **Adaptable Environment Tolerance:** Achieve optimal performance even in challenging conditions, cooling effectively in environments exceeding 35°C.
- **Temperature Management:** Experience chipset temperatures that are 30% cooler than traditional air-cooled servers.
- **Power Efficiency:** Slashing fan power by 50%, SmartPlate System saves up to 4kW per rack.
- **Noise Reduction:** Achieve a quieter operational environment with a significant 4X lower noise level.

Experience hassle-free liquid cooling for your servers with zero maintenance throughout their lifetime and no modifications needed for your facilities. **Cool smarter, not harder.**

Physical Specifications

Description	Value
Processor Compatibility	Intel 4th and 5th Gen Xeon (Sapphire & Emerald Rapids) AMD 4th Gen EPYC (Genoa)
SmartPlate Dimensions	110mm(L) x 82mm (W) x 23mm (H) *length and width determined by socket size
System Weight	1300g (1U form factor) 2000g (2U form factor)
System Volume	70in^3 (1U form factor) 350in^3 (2U form factor)
Supply Power	7W @ 12V (1U form factor) 19W @ 12V (2U form factor)

Performance Specifications

Description	Value
TDP Rating	Up to 850W (1U form factor) Up to 1,200W (2U form factor)
Air Flow	136 CFM (1U form factor) 192 CFM (2U form factor)
Inlet Air Temperature	55°F to 95°F (exceeds ASHRAE standards)
Coolant Fluid	PG25; Water-based coolants
Survival Temperature	35°F to 140°F

Patented Technology, Additional Patents Pending

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